## / Revised record

| | | | | | |
|---|---|---|---|---|---|
| A | 2016-5 | | | | |
| B | 2019-4-20 | | | | |
| C | 2021-10-26 | 4 | | | |
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## / Descriptions

SOT-363 PNP Double silicon PNP transistor in a SOT-363 Plastic Package.

## / Features

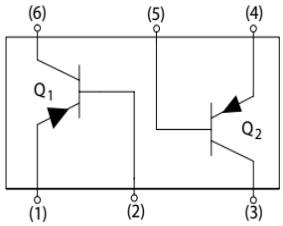
, MMDT5551

High voltage, complementary Pair with MMDT5551. HF Product.

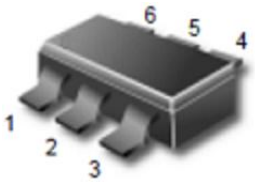
## / Applications

General purpose high voltage amplifier.

## / Equivalent Circuit




## / Pinning




PIN 1 4 Emitter PIN 2 5 Base PIN 3 6 Collector

## / $h_{FE}$ Classifications & Marking

See Marking Instructions.

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|

## / Marking Instructions




● “1”

2L

***:

Note:

● “1” Pin

2L Product Type Code

***: Lot No. Code, code change with Lot No.

## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

**/ M**

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Note:

1 150 180 60 90sec;

2 245±5 5±0.5sec;

3 2 10℃/sec.

1.Preheating:150~180℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

## / Resistance to Soldering Heat Test Conditions

0

260±5℃ 10±1 sec. Temp.:260±5℃ Time:10±1 sec

## / Packaging SPEC.

/ REEL

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: $mm^3$) | | |
|---|---|---|---|---|---|---|---|---|
| | | | | | | | 盒 | 箱 |
| | | | | | | 〃 | | |